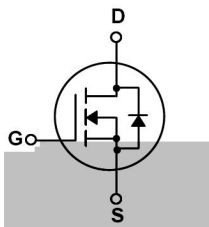


/ Descriptions

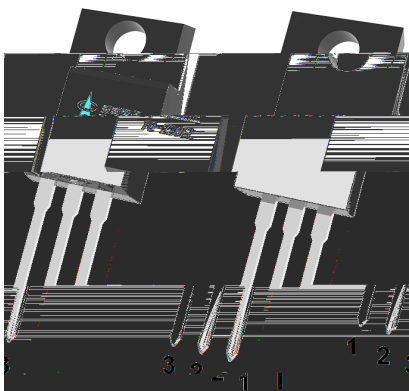
/ Features

/ Applications

/ Equivalent Circuit



/ Pinning

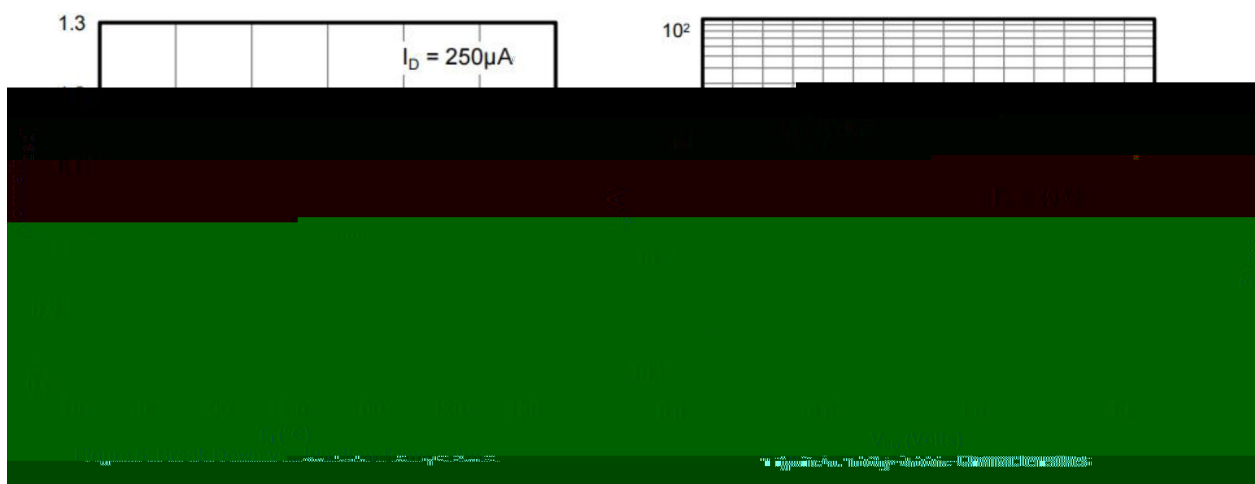
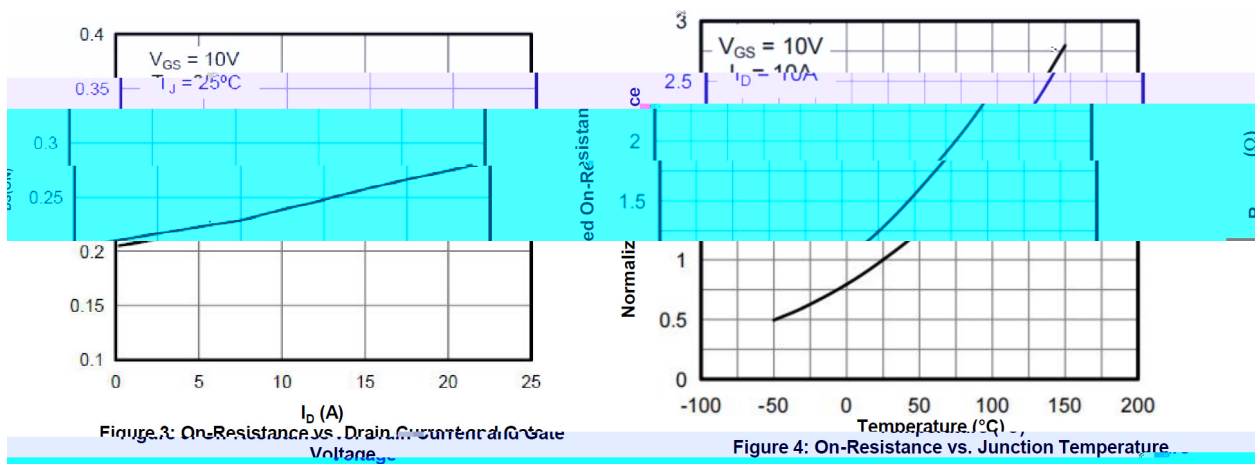
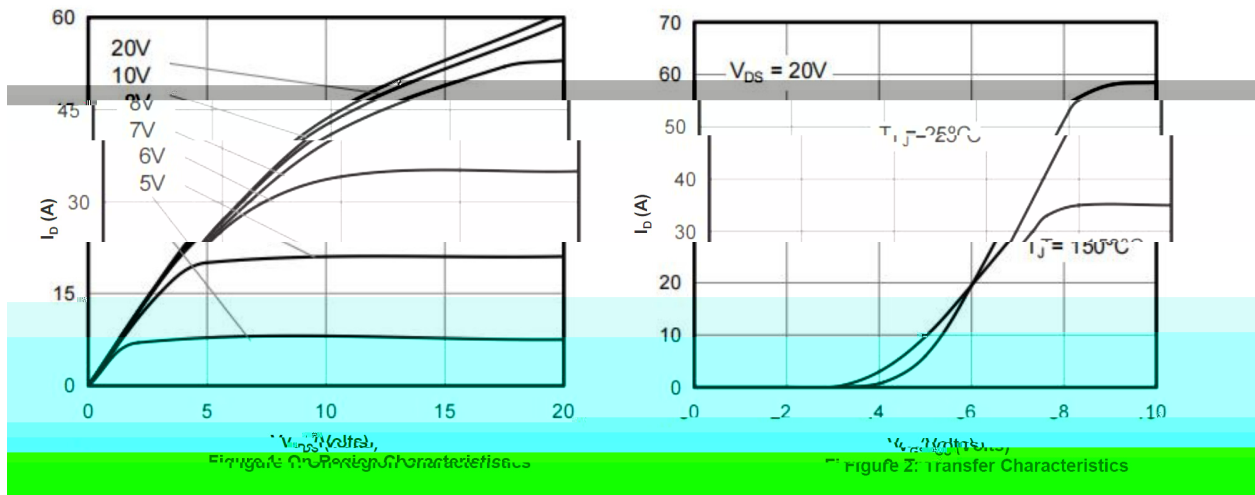


/ Marking

/ Electrical Characteristics(Ta=25)

		μ				

/ Electrical Characteristic Curve



/ Electrical Characteristic Curve

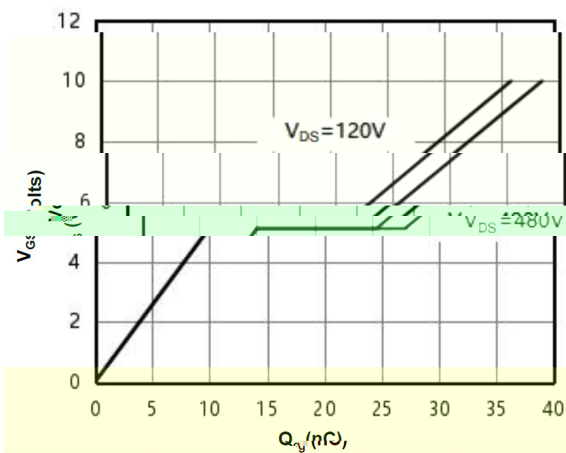


Figure 7: Gate Charge Characteristics

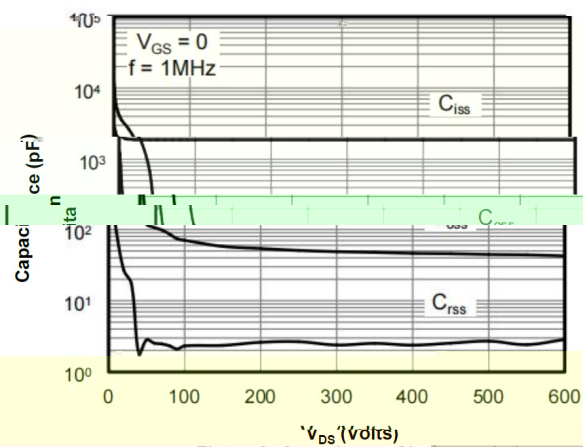


Figure 8: Capacitance Characteristics

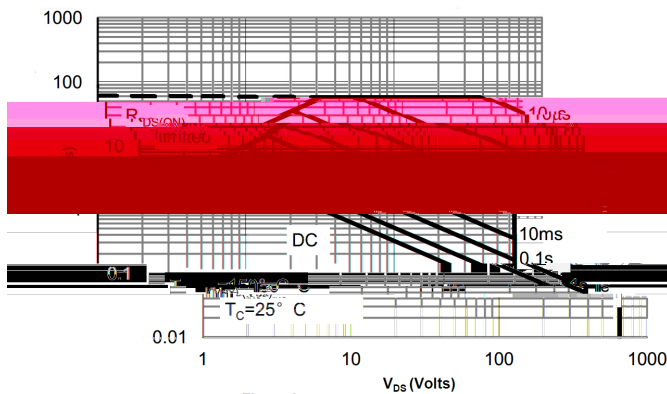


Figure 9: Maximum Forward Biased Safe Operating Area

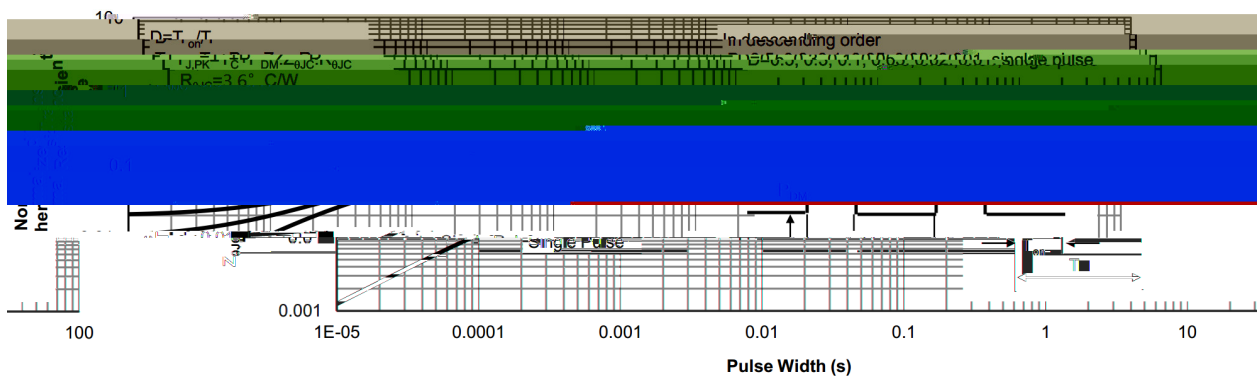
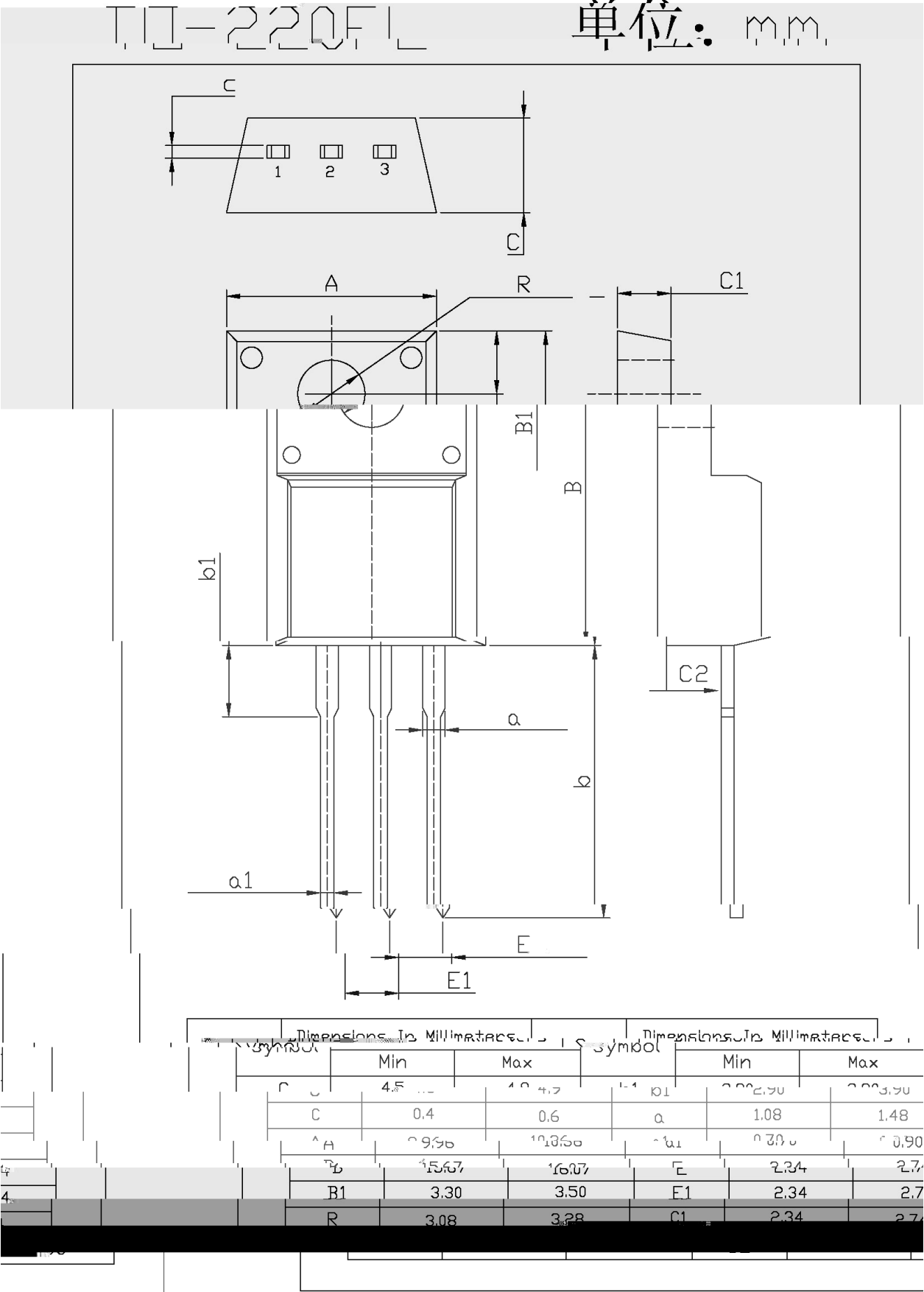
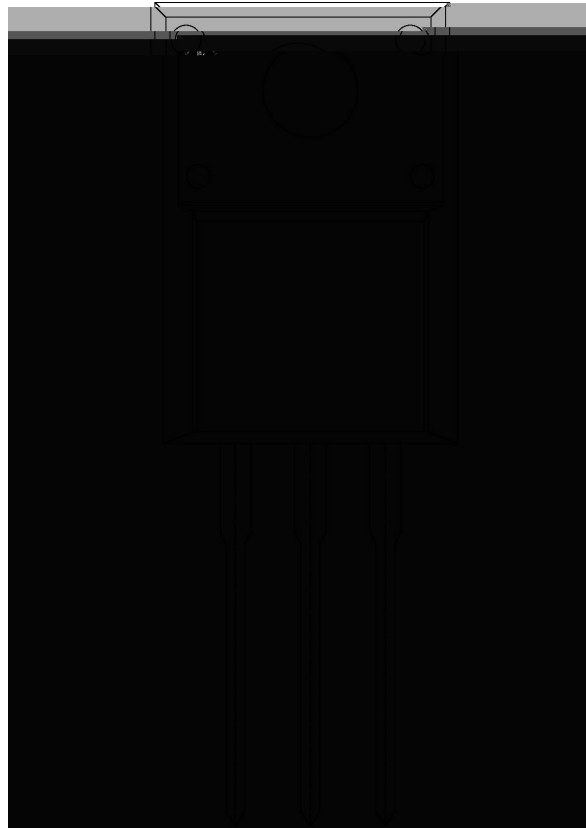


Figure 10: Normalized Maximum Transient Thermal Impedance

/ Package Dimensions



/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)

/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.